

2SK3650-01L,S,SJ

FUJI
ELECTRIC

200304

FUJI POWER MOSFET Super FAP-G Series

N-CHANNEL SILICON POWER MOSFET

■ Features

High speed switching
Low on-resistance
No secondary breakdown
Low driving power
Avalanche-proof

■ Applications

Switching regulators
UPS (Uninterruptible Power Supply)
DC-DC converters

■ Maximum ratings and characteristicAbsolute maximum ratings

● (Tc=25°C unless otherwise specified)

Item	Symbol	Ratings	Unit
Drain-source voltage	V _{DS}	150	V
	V _{DSX} *5	120	V
Continuous drain current	I _D	±33	A
Pulsed drain current	I _D (puls)	±132	A
Gate-source voltage	V _{GS}	±30	V
Repetitive or non-repetitive	I _{AR} *2	33	A
Maximum Avalanche Energy	E _{AS} *1	169	mJ
Maximum Drain-Source dV/dt	dV _{DS} /dt *4	20	kV/μs
Peak Diode Recovery dV/dt	dV/dt *3	5	kV/μs
Max. power dissipation	P _D	T _a =25°C	1.67
		T _c =25°C	150
Operating and storage temperature range	T _{ch}	+150	°C
	T _{stg}	-55 to +150	°C

*1 L=228μH, V_{CC}=48V, T_{ch}=25°C, See to Avalanche Energy Graph *2 T_{ch}≤150°C

*3 I_F≤-I_D, -di/dt=50A/μs, V_{CC}≤BV_{DSS}, T_{ch}≤150°C *4 V_{DS}≤150V *5 V_{GS}=-30V

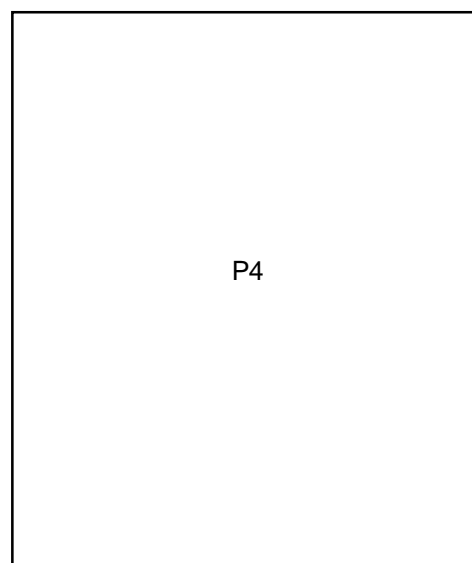
● Electrical characteristics (T_c =25°C unless otherwise specified)

Item	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain-source breakdown voltage	V _{(BR)DSS}	I _D =250μA V _{GS} =0V	150			V
Gate threshold voltage	V _{GS(th)}	I _D = 250μA V _{DS} =V _{GS}	3.0		5.0	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =150V V _{GS} =0V			25	μA
		V _{DS} =120V V _{GS} =0V			250	
Gate-source leakage current	I _{GSS}	V _{GS} =±30V V _{DS} =0V		10	100	nA
Drain-source on-state resistance	R _{DS(on)}	I _D =11.5A V _{GS} =10V		54	70	mΩ
Forward transconductance	g _{fs}	I _D =11.5A V _{DS} =25V	8	16		S
Input capacitance	C _{iss}	V _{DS} =75V		1150	1730	pF
Output capacitance	C _{oss}	V _{GS} =0V		200	300	
Reverse transfer capacitance	C _{rss}	f=1MHz		17	26	
Turn-on time t _{on}	td(on)	V _{CC} =48V I _D =11.5A		13	20	ns
	t _r	V _{GS} =10V		15	23	
Turn-off time t _{off}	td(off)	R _{GS} =10 Ω		34	51	
	t _f			15	23	
Total Gate Charge	Q _G	V _{CC} =48V		34	51	nC
Gate-Source Charge	Q _{GS}	I _D =23A		9	13.5	
Gate-Drain Charge	Q _{GD}	V _{GS} =10V		12.5	19	
Avalanche capability	I _{AV}	L=228μH T _{ch} =25°C	33			A
Diode forward on-voltage	V _{SD}	I _F =23A V _{GS} =0V T _{ch} =25°C		1.10	1.65	V
Reverse recovery time	t _{rr}	I _F =23A V _{GS} =0V		130		ns
Reverse recovery charge	Q _{rr}	-di/dt=100A/μs T _{ch} =25°C		0.6		μC

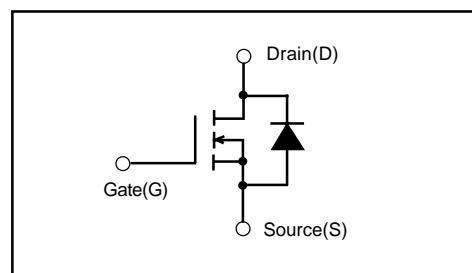
● Thermalcharacteristics

Item	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal resistance	R _{th(ch-c)}	channel to case			0.833	°C/W
	R _{th(ch-a)}	channel to ambient			75.0	°C/W

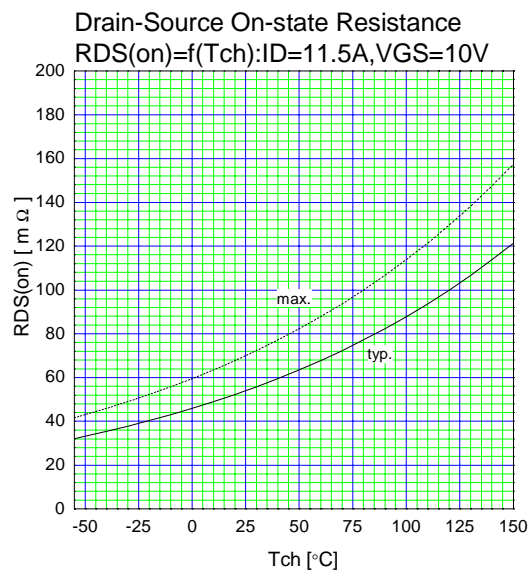
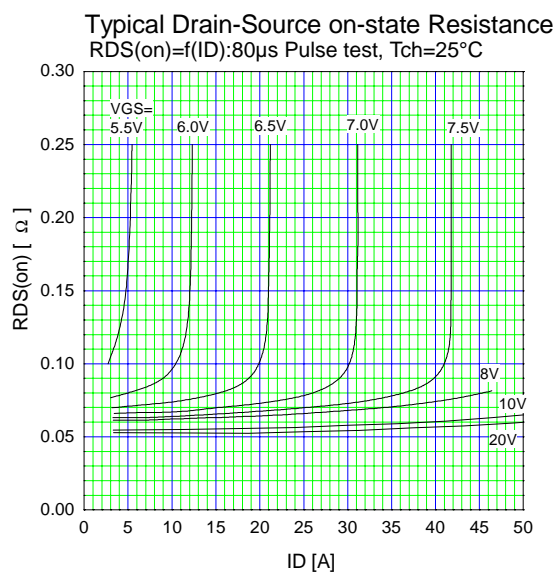
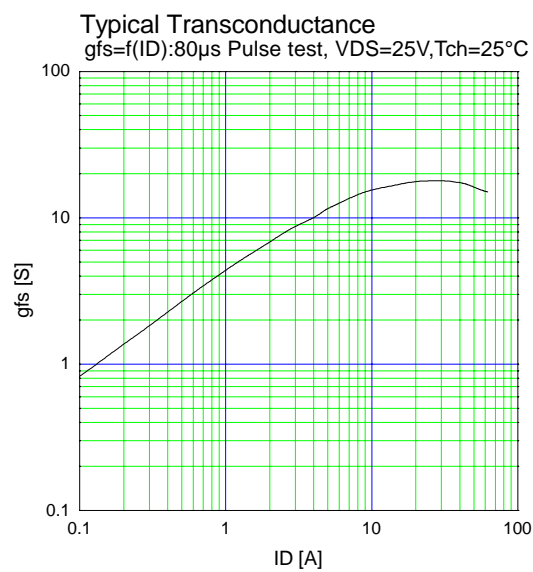
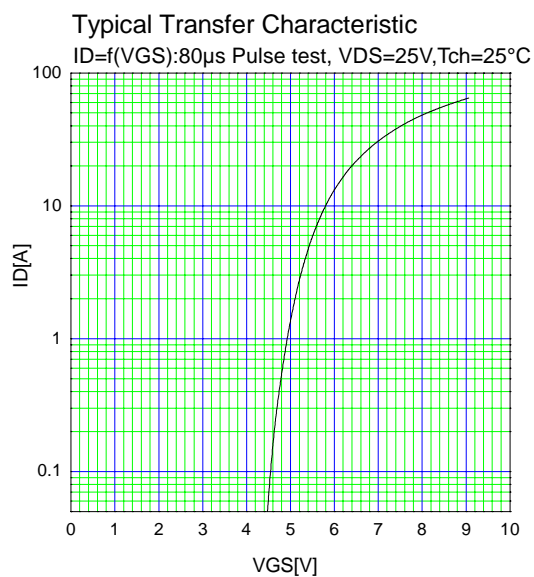
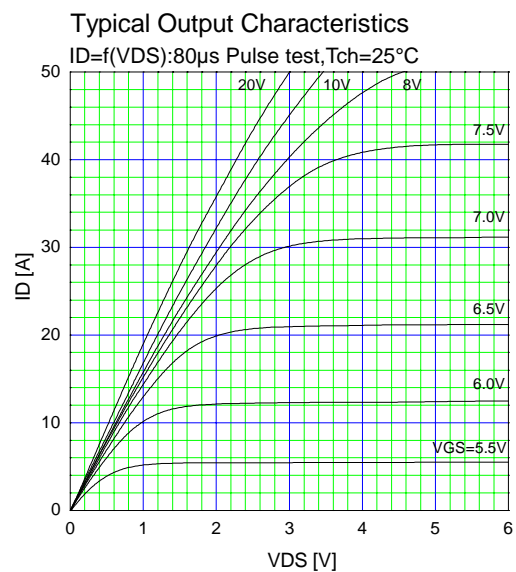
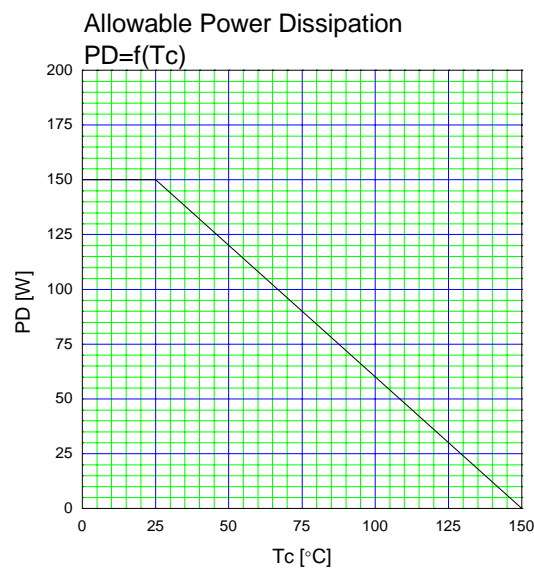
■ Outline Drawings [mm]

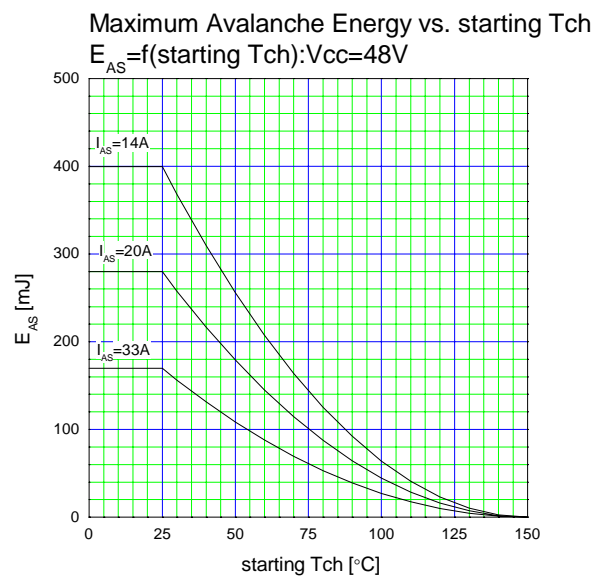
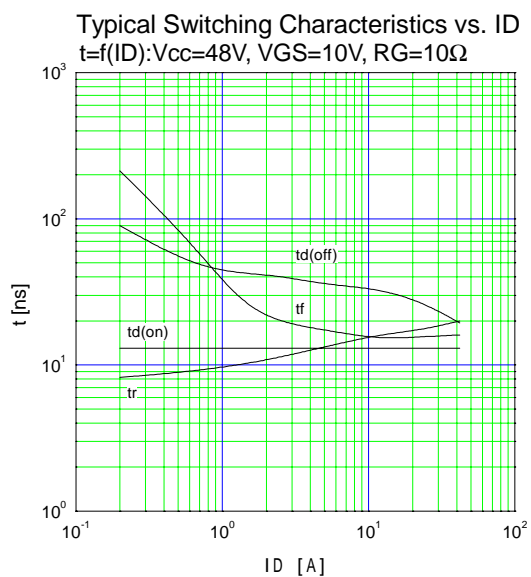
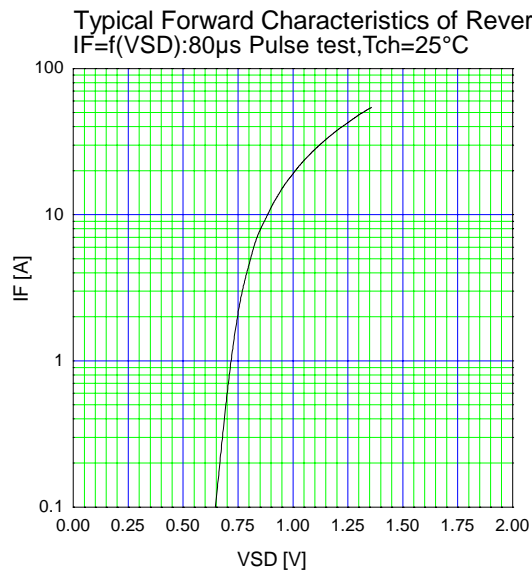
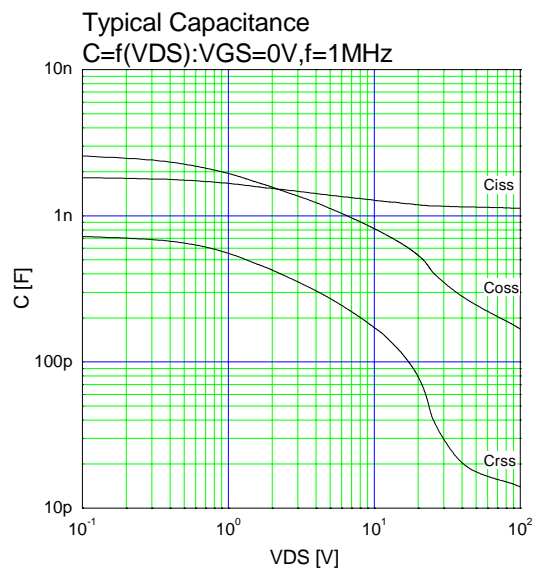
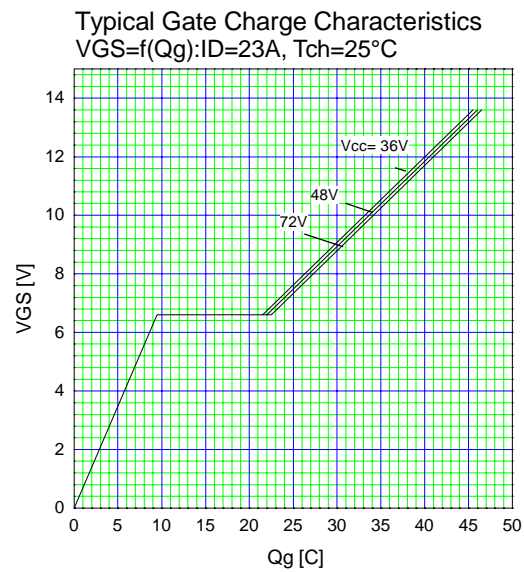
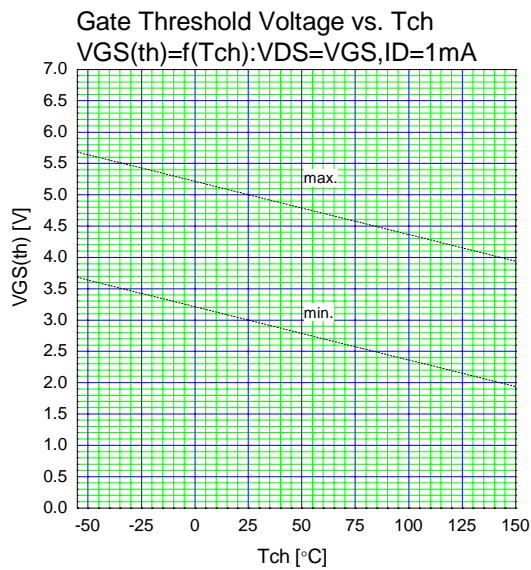


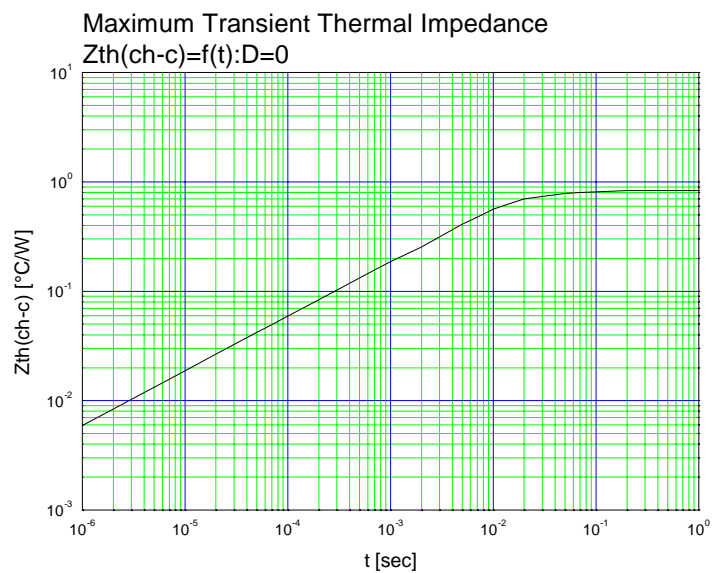
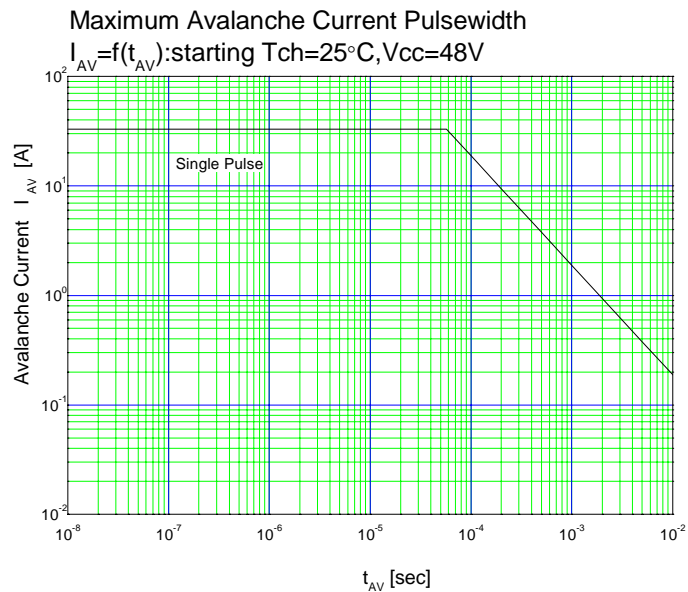
■ Equivalent circuit schematic



Characteristics







Outline Drawings (mm)

